Development of New Readout Electronics for the ATLAS LAr Calorimeter at the sLHC

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on behalf of the ATLAS Liquid Argon Calorimeter Group

Topical Workshop on Electronics in Particle Physics
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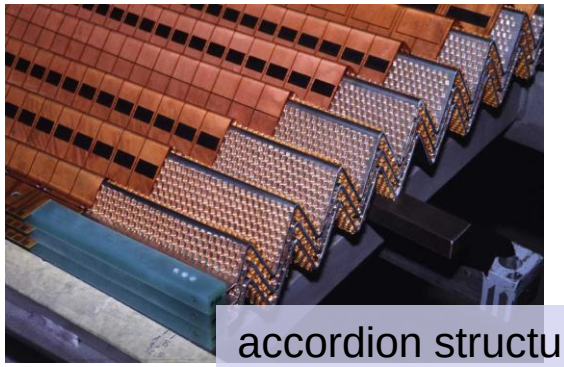
Outline

- The ATLAS Calorimeter Readout
- Upgrade Scenario and Readout Architecture for the sLHC
- Radiation Hard Front-end Electronics
- High Bandwidth Back-end Electronics
- Outlook

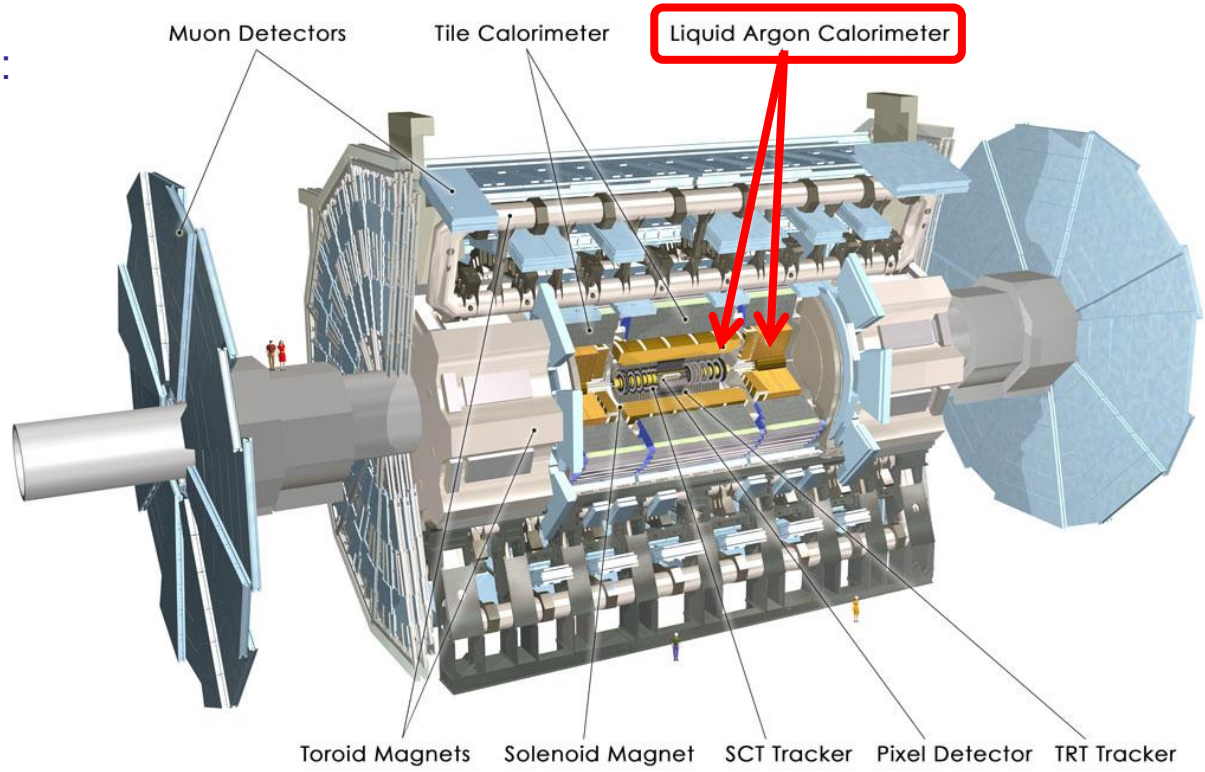
The ATLAS Liquid Argon Calorimeters

- 4 high granularity LAr calorimeters:
  - e.m. barrel Pb/LAr
  - e.m. endcap Pb/LAr
  - had. endcap Cu/LAr
  - forward calorimeter Cu/W/LAr

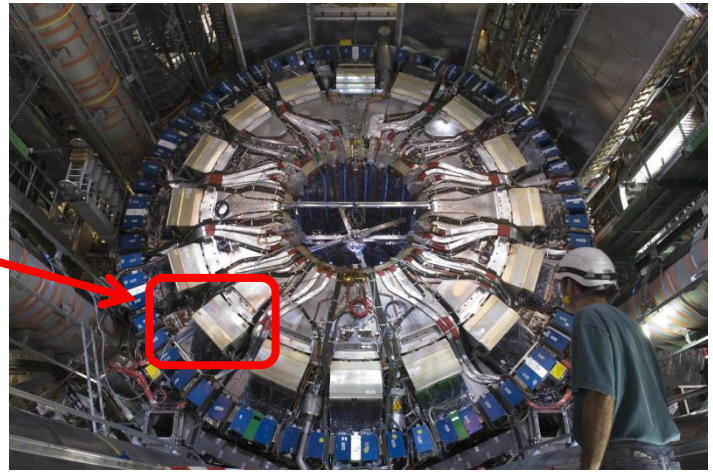


accordion structure

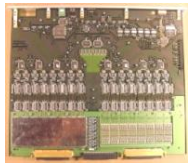
- 182486 readout channels
- 40 MHz proton-proton collision rate



- front-end and trigger-sum electronics
  → on-detector in radiation environment
- back-end electronics and more trigger logic
  → shielded counting room



Current Layout of the Calorimeter Readout



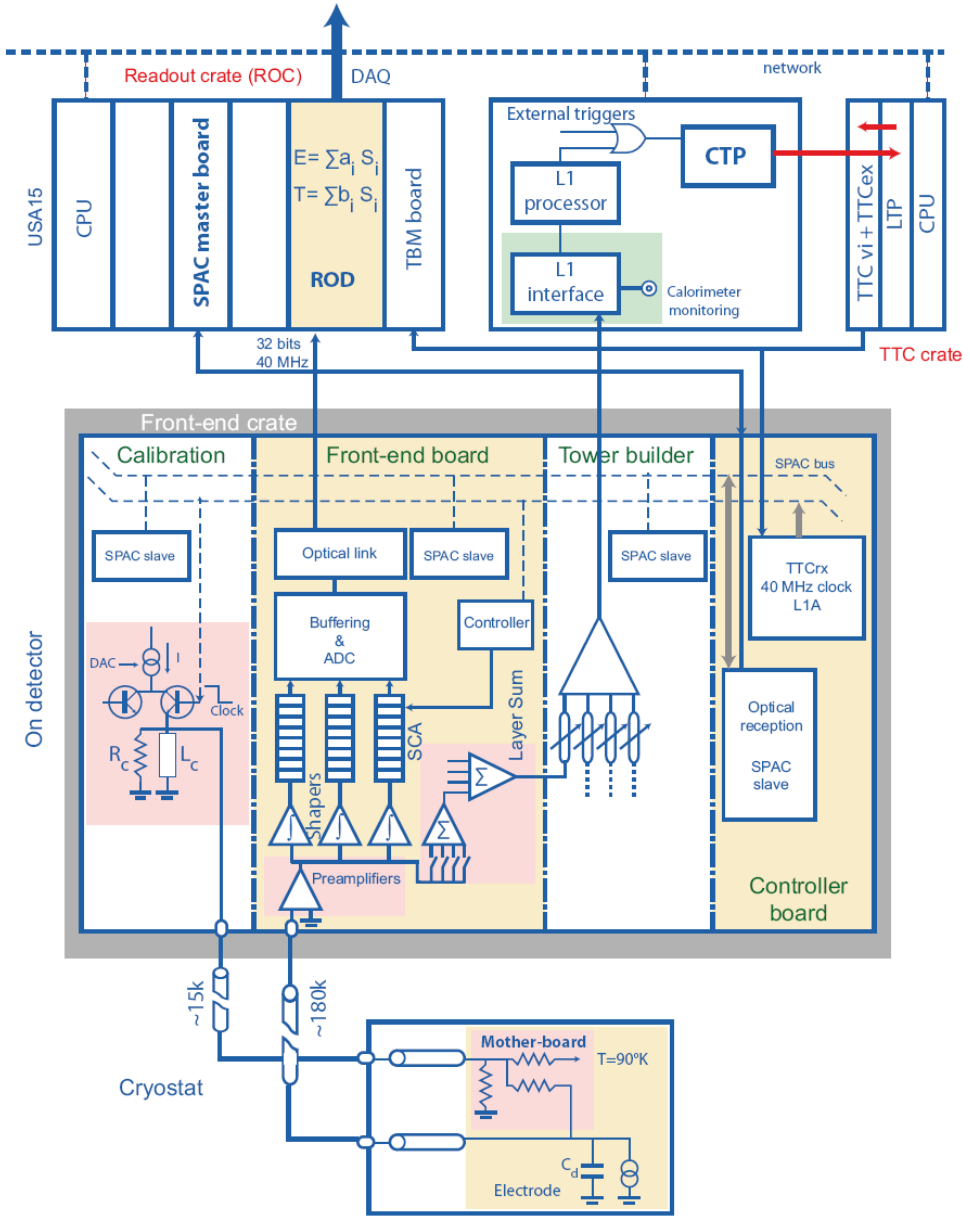
- 1524 front-end boards (FEB)
  - → up to 128 channels
  - → preamp, pulse shaping, buffer and sampling
- in 58 front-end crates
  - → low-voltage power supplies (LVPS)

- connected to off-detector electronics by 1600 optical links

- 192 read-out driver boards (ROD)
  - → digital filter

- 800 optical links to DAQ PCs

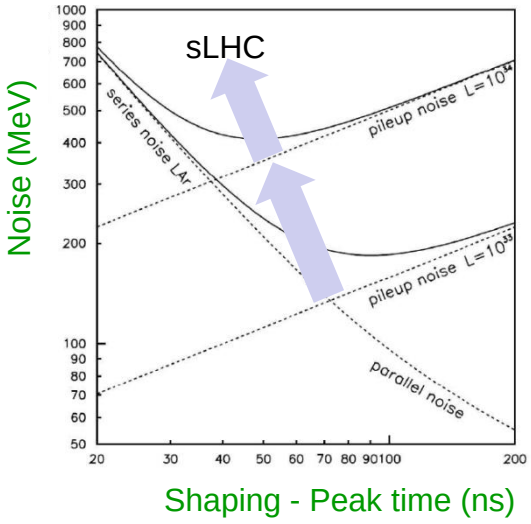
- 68 read-out system PC's (ROS)
  - → DAQ and high-level trigger buffer

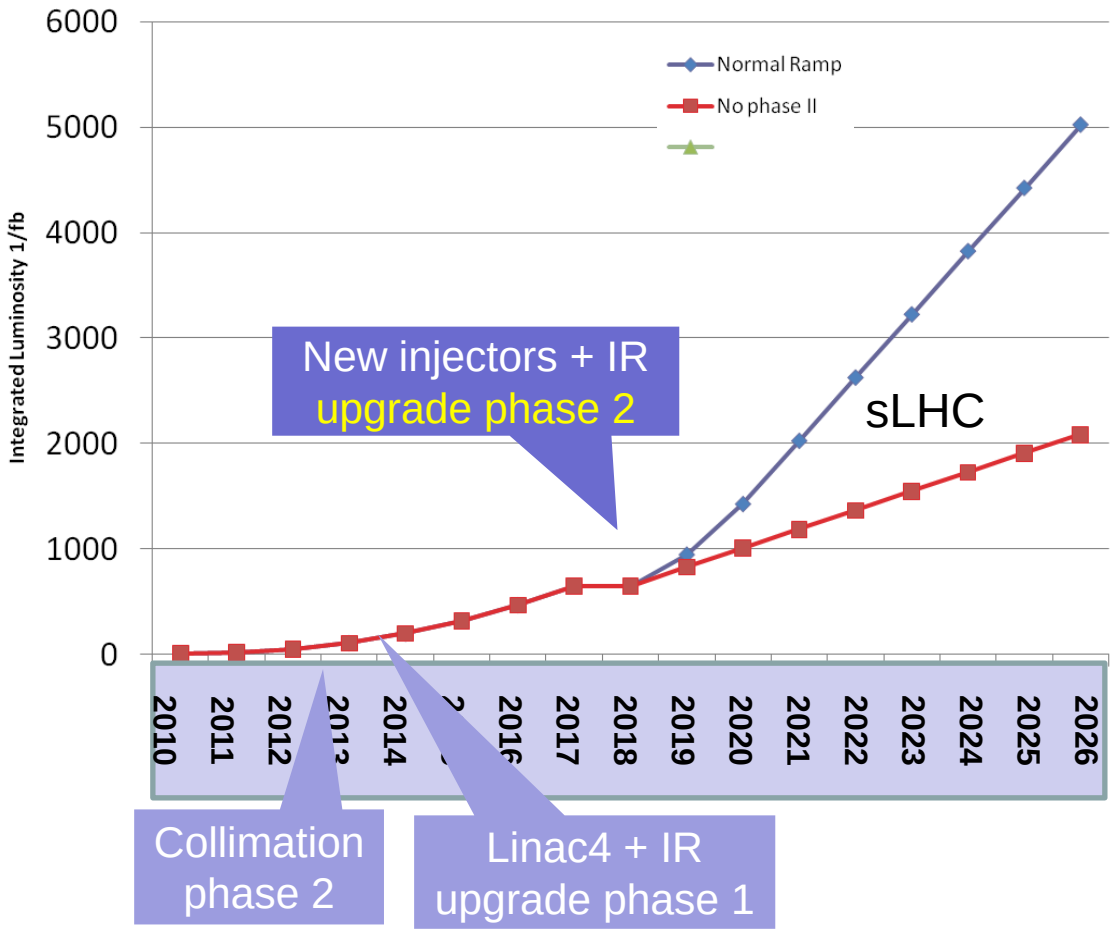


Upgrade to super-LHC

- LHC upgrade in 2 phases
  - sLHC starts in ~2019/20

- sLHC challenges
  - 10x more radiation
  - up to 20 times more pile-up events
- readout challenges
  → rad. hardness
  → same power consumption
  → same physics performance
    - same dynamic range
    - noise suppression



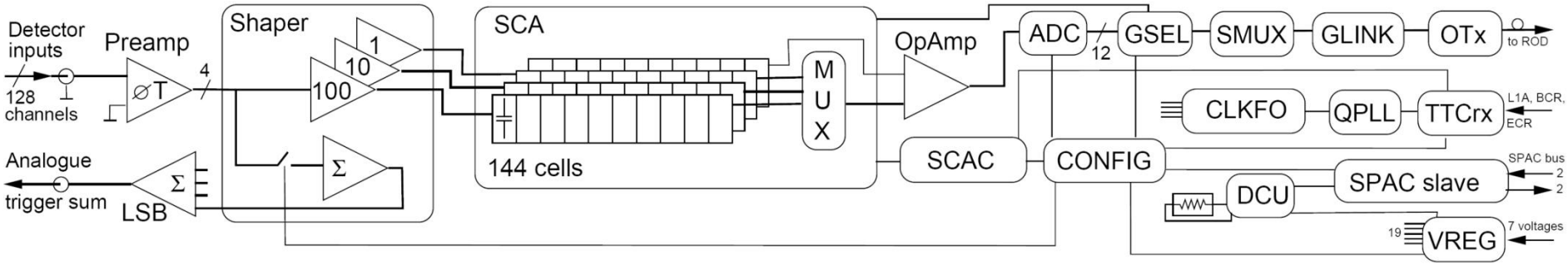


peak luminosity:

10^{34} cm^{-2}s^{-1} → 3 x 10^{34} cm^{-2}s^{-1} → 10 x 10^{34} cm^{-2}s^{-1}

- new calorimeter readout for 2019/20

Current Front-End Limitations



- complex board architecture:
  - 11 ASICs with different technologies
    - some obsolete (DMILL, ...)
  - 19 voltage regulators
  - analog pipelines (SCA)
  - 80 W/board
  - water-cooled

- performance limitations:
  - level-1 trigger rate only up to 100 kHz
  - max. latency 2.5 μs
  - min. level-1 intervals 125 ns
  - fixed analog trigger sums (8-32 channels/trigger tower)

- main concern:
  - qualified for 10 years of normal LHC operation (incl. safety factors)
  - sLHC: 300 Krad and 10^{13} neq/cm^2
  - small number of spares (6%)

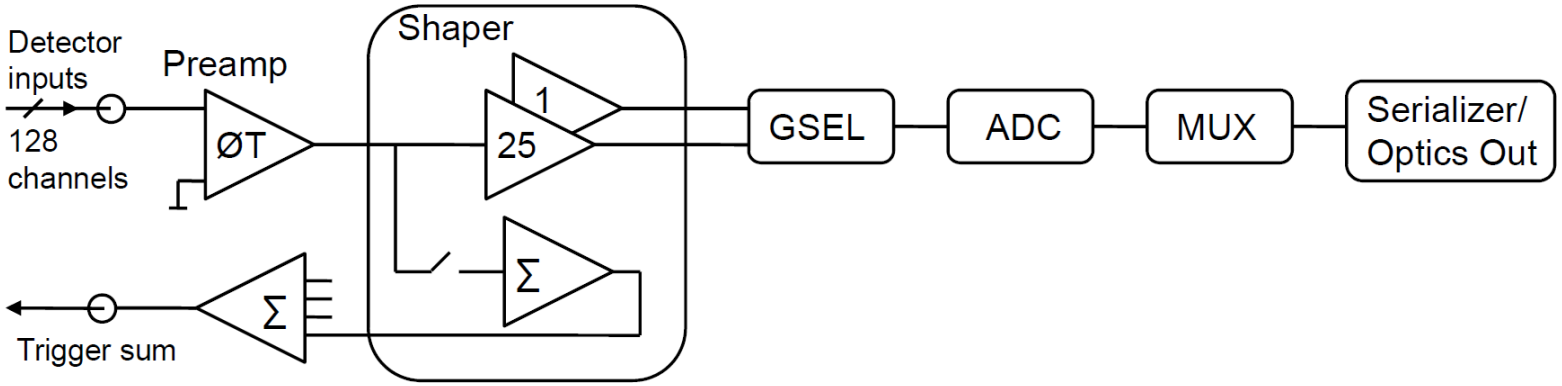
LHC Radiation Tolerance Criteria

Radiation		Estimated	DMILL	Commercial Process
Type	Units	Level	RTC	RTC
TID	Gy	50	525	1700
NIEL	1 MeV equiv. n/cm^2	1.6×10^{12}	1.6×10^{13}	1.6×10^{13}
SEE	Hadrons (> 20 MeV)/cm^2	7.7×10^{11}	7.7×10^{12}	7.7×10^{12}

- replacement of single components impossible

→ new front-end boards based on today's technology with same power budget

New Front-End Prototype Design



- evaluate different options:
  - shaper and gain settings
  - analog ↔ digital pipeline
  - on-detector ↔ off-detector pipeline
  - analog ↔ digital gain selector

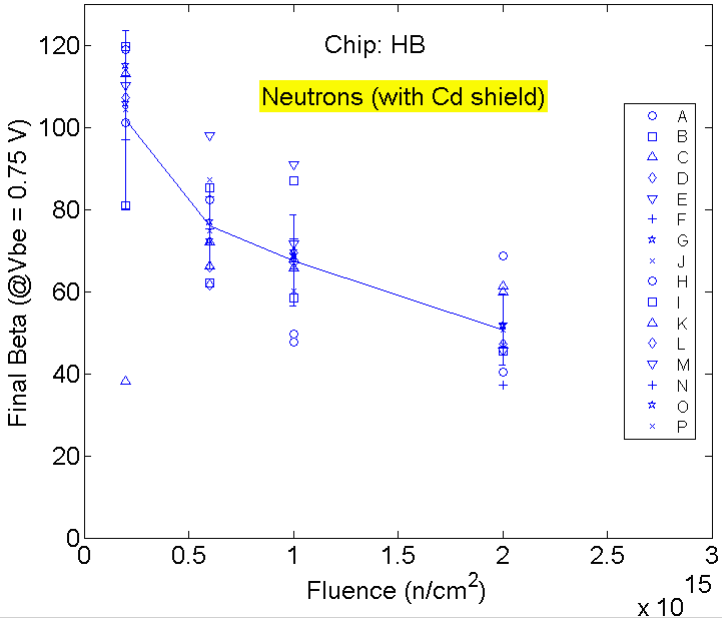
  - analog trigger sums
    → possibility to keep current level-1 trigger system

- R&D baseline:
  - shaping and digitization at high rate
    → 128 channels at 40 MHz
  - transfer rate → 100 Gb/s per FEB
  - rad. hard optical links at ~10 Gb/s
  - fully digital off-detector trigger
    → digital pipeline on ROD
    → trigger sums on ROD and calorimeter trigger
    → more flexible and higher trigger granularity

Analog Front-End R&D

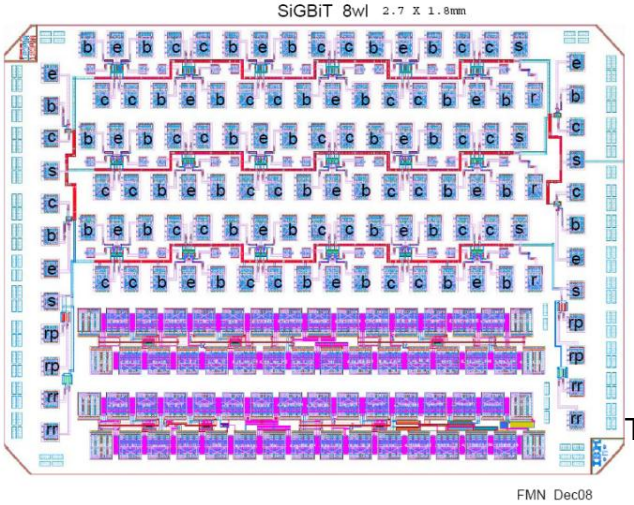
- SiGe IBM 8WL BiCMOS process (0.13 micron)
  - technology also studied for ATLAS silicon strip tracker readout and ILC detectors

- irraditation tests with spare IBM test structures
- example: final gain after neutron irradiation:
  - β>50 at 10^{14} neq/cm^2
  - dispersion due to irregular test structure



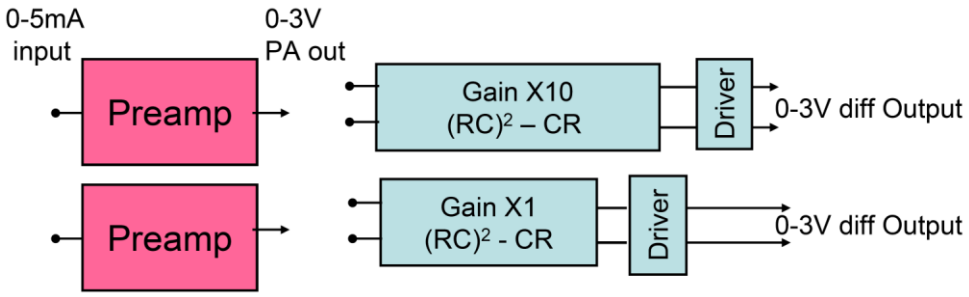
Tr.	Emitter size
A	.12x.52x1
B	.12x1x1
C	.12x2x1
D	.12x3x1
E	.12x4x1
F	.12x8x1
G	.12x12x1
H	.12x1x2
I	.12x3x2
J	.12x8x2
K	.12x12x2
L	.12x3x4
M	.12x8x1
N	.12x3x6
O	.12x8x6
P	.12x16x6

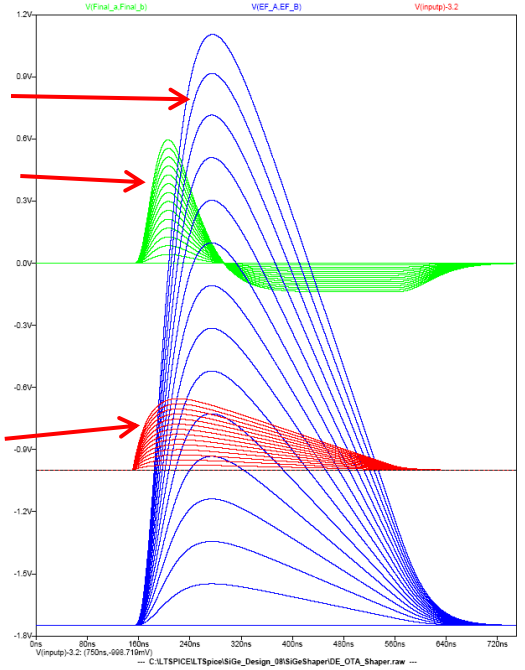
- own chiplet submitted end of 2008
- irradiation program finished and data is being analysed



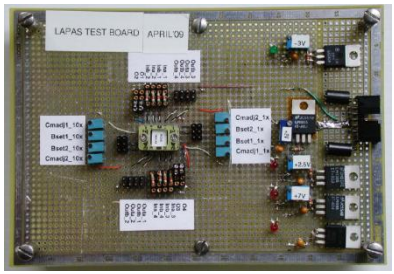
Test Structure Chiplet
2.7mm x 1.8mm

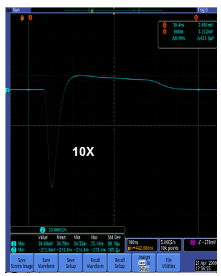
Preamp and Shaper Prototype

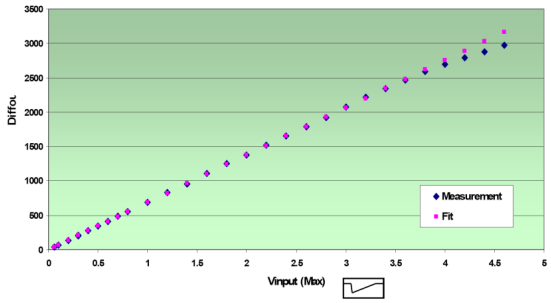


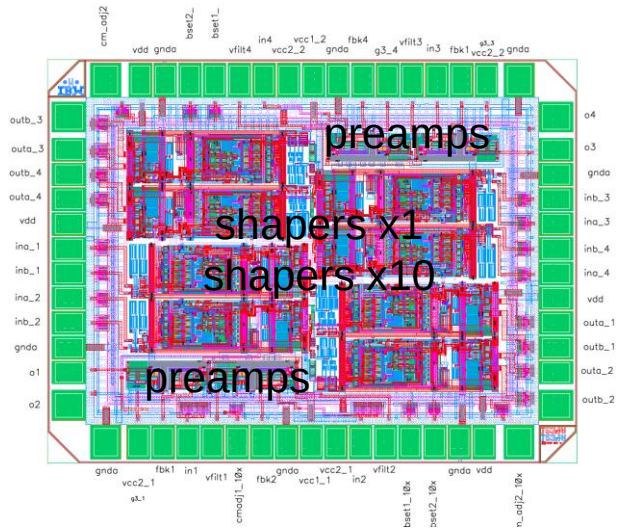


- Preamp
  - low noise ~0.25nV/√Hz, high dynamic range
  - based on low noise line-terminating preamplifier circuit topology presently used in ATLAS LAr calorimeter
- Shaper
  - fully differential
  - robust performance in low signal environment, excellent pickup rejection on and off chip
- < 0.2% non-linearity
- power ~ 40 mW / preamp and ~ 100 mW /shaper









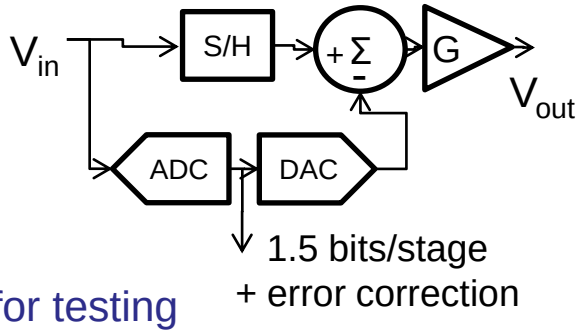
LAr Chiplet
2mm X 2mm

- see: Parallel session A2 – ASICs – Mitch Newcomer

Mixed-Signal Front-End ADC

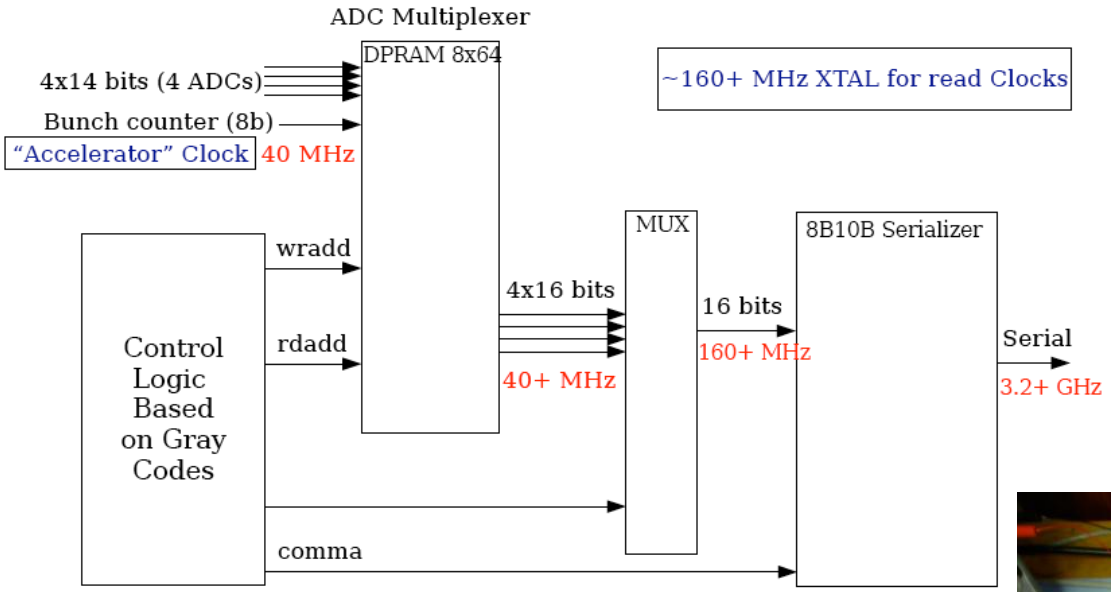
- ADC is the most challenging component in the new “baseline” architecture
  - 15(16) bit dynamic range - 12 bit resolution – 40 MSPS
  - radiation tolerant and immune to single event effects (SEE)
- R&D strategies:
  - evaluate commercial parts
    - planning to test several COTS ADCs:
      - AD9259 (14/12 bit), ST-RHF1201 (12 bit), TI ADS5281 (12 bit)
  - development of a custom ADC
    - started with IBM 8HP SiGe → 8RF CMOS is now the candidate technology
    - shown to be radiation hard
    - lower cost compared to SiGe

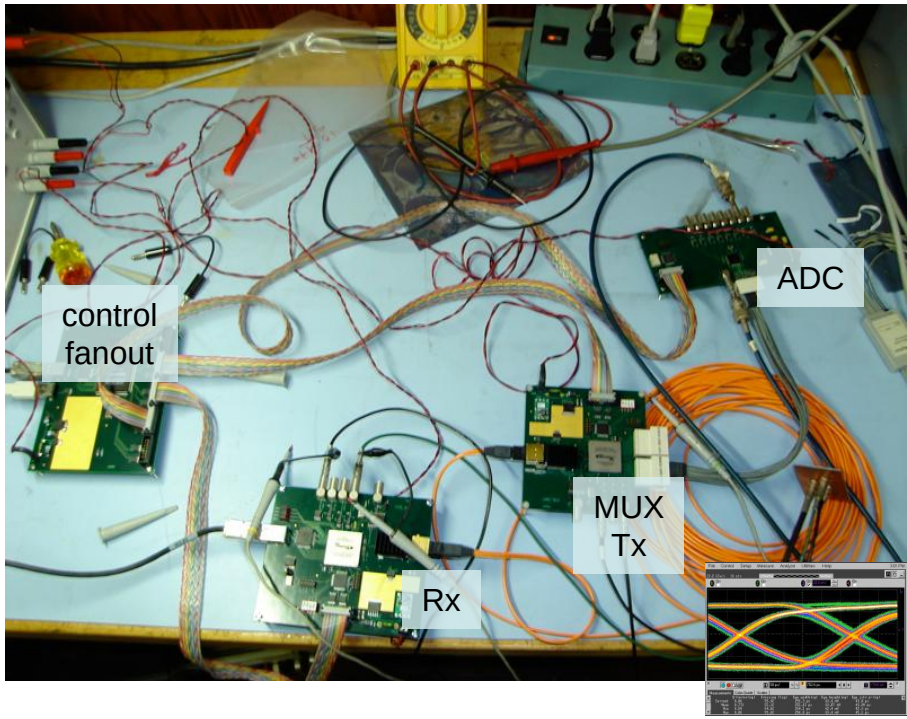
- 12 bit pipeline ADC with 1.5 bits/stage and digital error correction
  - on-board correction will require rad-hard redundant memory for calibration constants
- main building blocks of custom pipeline ADC:
  - operational trans-impedance amplifier (OTA)
  - core for the S/H and Multiplying DAC subsystems
  - S/H capacitor important since noise ~ $\sqrt{kT/C}$



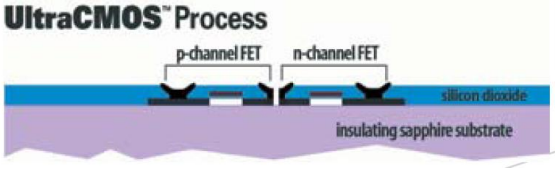
- chiplet submitted to CERN/MOSIS with OTA + cascade of 2 T/H for testing
- expected back by late October

Digital Test of the Front-End



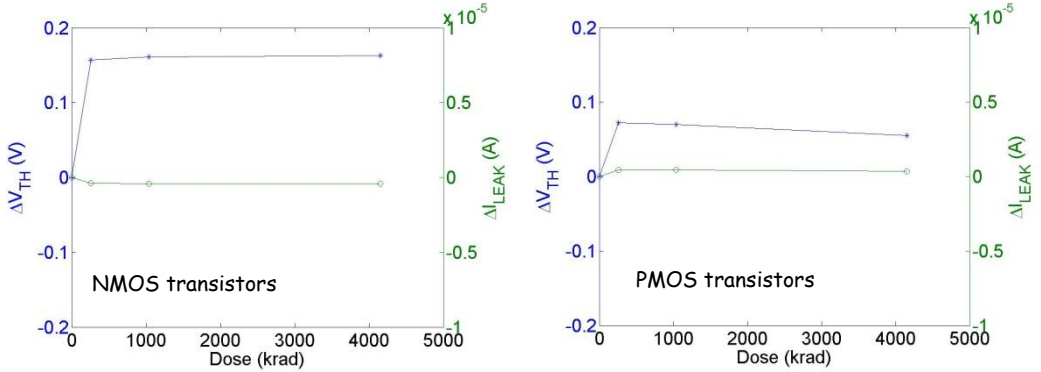


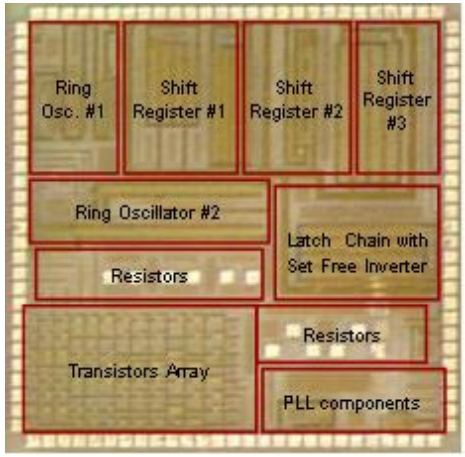
Raditation Hard Optical Links



- Silicon-on-Sapphire (SoS) technology:
  - 0.25 µm UltraCMOS by Peregrine Semiconductors
  - low power, low cross talk → good for mixed-signal ASIC designs
  - economical for small to medium scale ASIC development

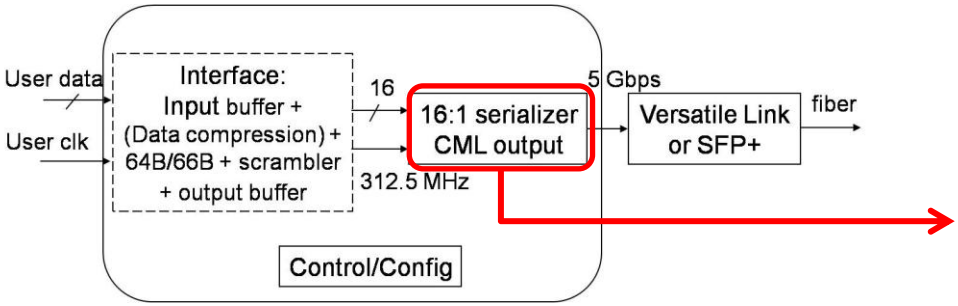
- TID and SEE radiation tests performed in 2007:
  - gamma irradiation with ^{60}Co source up to 4 Mrad

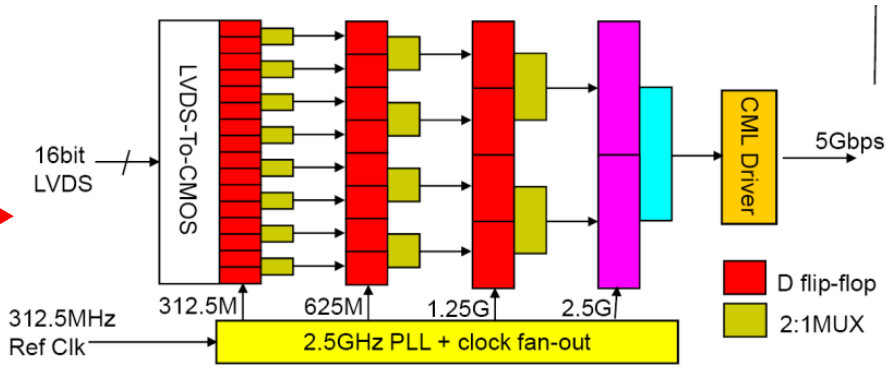




  - with grounded substrate: small leakage currents (250 nA) and small threshold voltage increase
  - irraditation in 230 MeV proton beam
    - no SEE observed in shift registers at a flux of 7.7×10^{8} proton/cm^2/sec
    - still correctly functioning after total fluences of 1.9×10^{15} p/cm^2 (106 Mrad(Si))

Link On Chip Prototype #2 (LOC2)



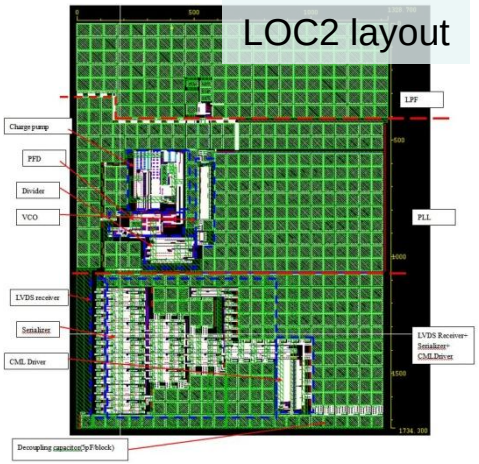


- LOC1 prototype suffered of high jitter, now LOC2:
- 5 Gbps 16:1 serializer
  - 3 stages of 2:1 MUX
  - last stage: 2 fast transmission gate D-flip-flops
- input data and ref. clock in LDVS
- output in CML at 5 Gbps → CERN Versatile Link
  - Parallel Session B5 - Optoelectronics and Links: Paulo Moreira, Jan Troska
- transmission bit error rate lower than 1×10^{-12}
- power consumption is below 500 mW or less than 100 mW/Gbps.
- post-layout simulation show that critical components meet LOC2 requirements (PLL, DFF, CML driver)

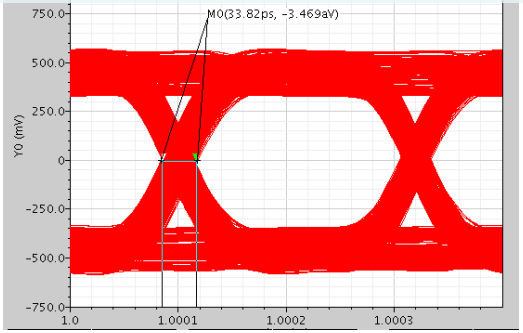
- user interface will be implemented in FPGA for tests

- effort towards a 5 GHz LC-tank based PLL:
  - random jitter < 1 ps (RMS) achieved in simulations
  - needed for ultimate goal of a ~10 Gbps link

LOC2 layout

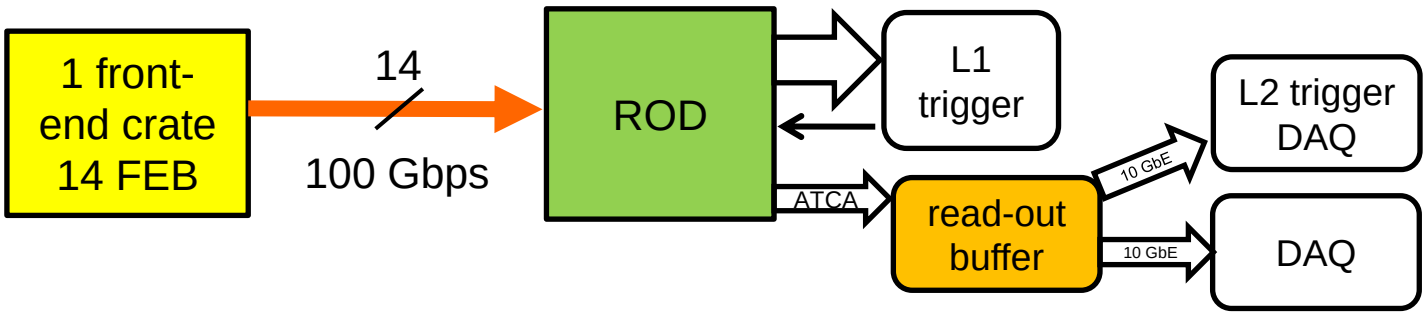


with ideal power source: TJ=34 ps



Readout Driver Upgrade

- 218 RODs in non rad-hard environment
- 1524 FEBs x 100 Gbps continuous data stream → 150 Tbps

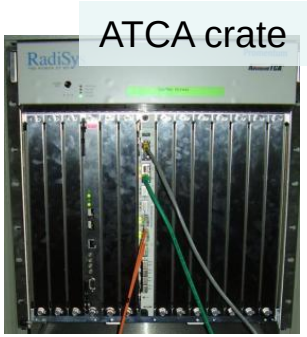


- 12-fiber optical connectors  MPO/MTP style → each 100 Gbps

- Xilinx & Altera FPGA embedded SERDES
- evaluate reduction of number of links by
  - latency lossless data compression/decompression algorithm
  - less bits at ADC

} front-end challenges

- FPGA based Digital Signal Processing
  - advantage of parallel data processing
- system level architecture: AdvancedTCA
  - take the advantage of industrial standard
  - shelf management protocols, power management, fast fabrics
- perform level 1 trigger sum digitally
  - flexible and fine granularity

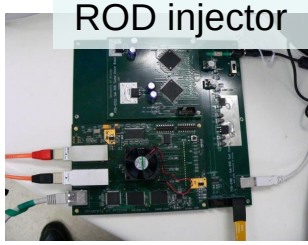


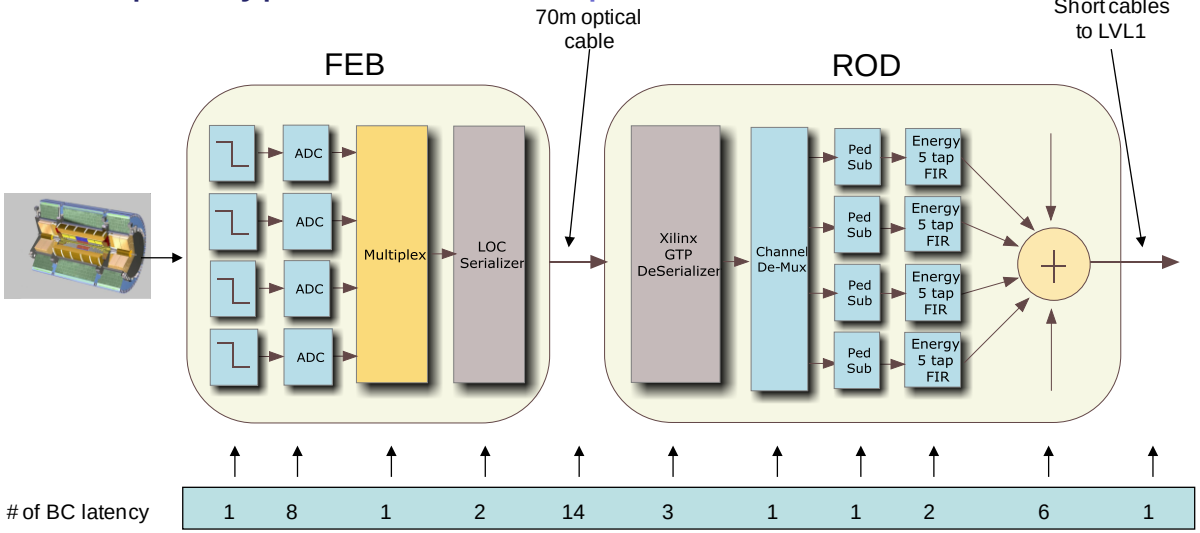
High Performance Digital Readout

- ROD prototypes with Xilinx Virtex 5 FX (XC5VFX70T)
- 75Gbit/s fiber optic transceiver Reflex Photonics + SNAP 12
- ROD injector test with Altera Statix GX II
- 6.5 Gbps/fiber transfer rate possible
  → with previous prototype: stable 2.4 Gbps/f. on 12 fibers

ATCA ROD prototype

ROD injector





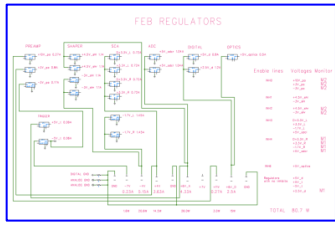
- digital linear FIR filter → FPGA embedded parallel DSPs (Xilinx Virtex 5 FX series, XC5VFX70T)
- digital level-1 trigger sums
  - pulse height and timing extracted from digitized pulse
  - time alignment to be evaluated → current ROD has only asynchronous data transfer

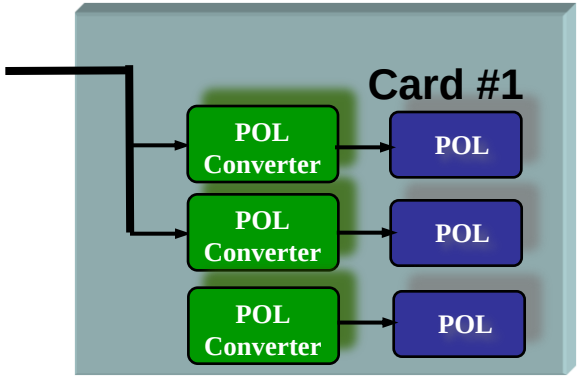
- total latency: 40 bunch-crossings → ~ 1 µs < currently allowed 2.5 µs

- more system level tests ongoing (level-1/2 digital buffers on ROD/ROB, remote DMA, ...)

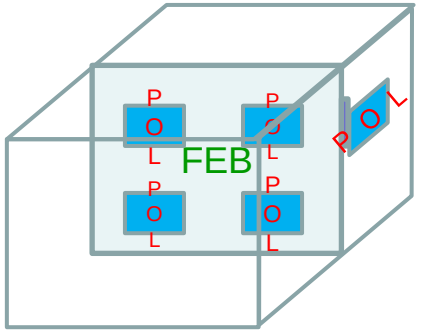
Radiation Hard Front-End Powering

- current power supply scheme:
  - 380 VAC/3 phases → 280 V DC → DC-DC converter w/ 7 voltages → 19 voltage regulators on FEB
- power budget remains approximately the same
- rationalization of the number and levels of the voltages
- use of point of load (POL) regulators





- new LVPS architectures:
  - Distributed Power Architecture
    - main converter + POLs
  - Intermediate Bus Architecture
    - higher main voltage + 2nd bus voltages + POL converters



- 2 POL tested in different positions inside front-end crate (FEC):
  - LTM4602 – 6A High Efficiency DC/DC µModule
  - IR3841 – Integrated 8A Synchronous Buck Regulator
- noise shielding necessary if inside FEC → ready for radiation tests

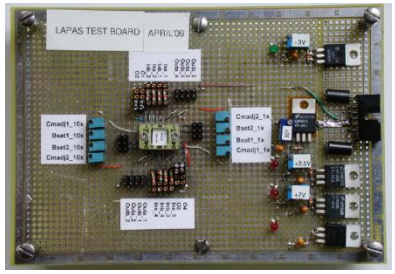
Summary and Outlook

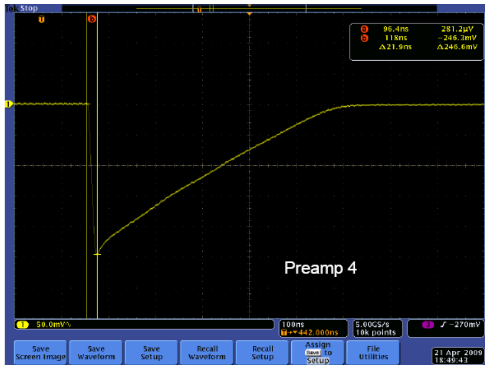
- Radiation levels and physics performance at sLHC requires replacement of front-end electronics of the ATLAS Liquid Argon calorimeter
- opportunity to apply modern technology and revise architecture:
  - trigger-less data transfer to off-detector electronics
  - fully digital trigger
- several major R&D challenges:
  - fast, rad-hard preamp, ADC and serial links
  - high bandwidth off-detector readout
- progress in all R&D activities
- more results expected soon, also on radiation and performance tests of recently submitted or received 8RF CMOS, SiGe and SoS chiplets

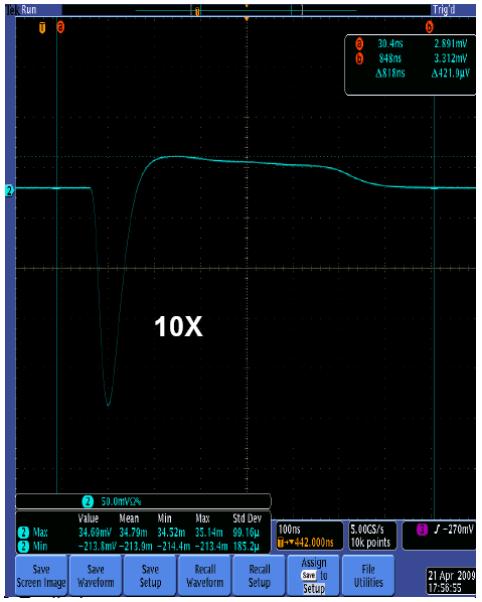
Backup

Preamp and Shaper Prototype Tests

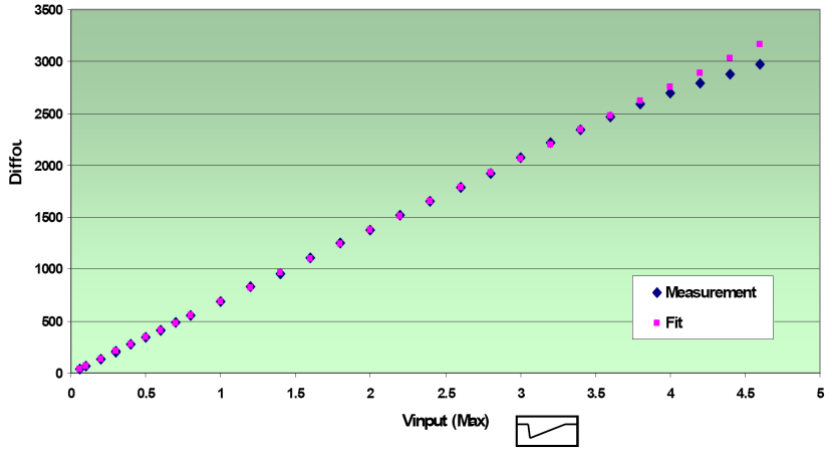
- Test board:





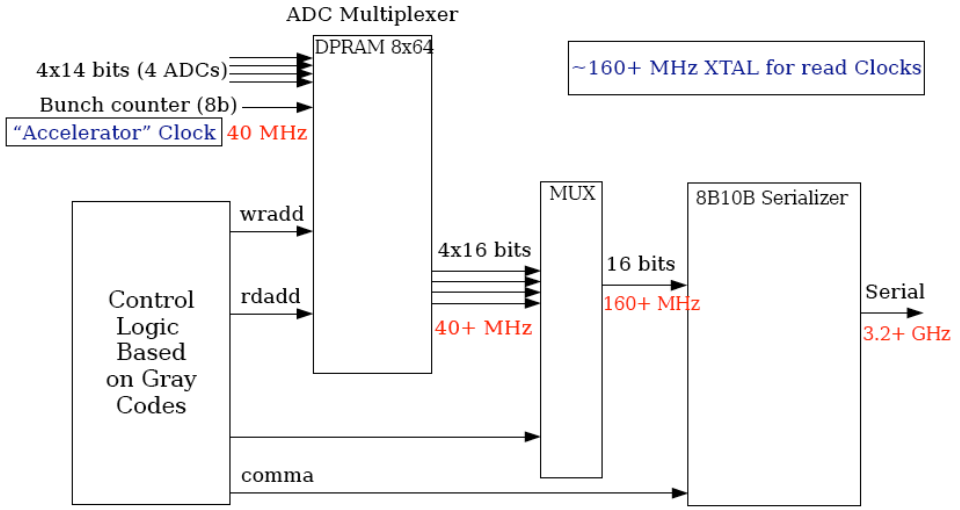


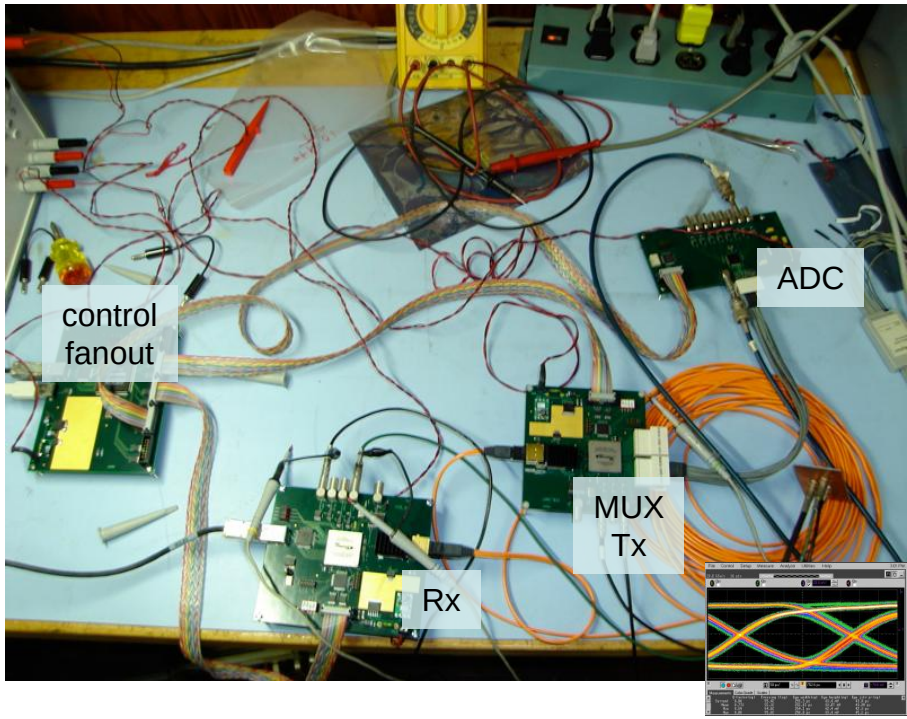
- Input
- Preamp
- Shaper
- preliminary linearity measurements:
- goal:
  - < 0.2% non-linearity
  - power ~ 40 mW / preamp
    ~ 100 mW /shaper
- radiation testing and data analysis is ongoing



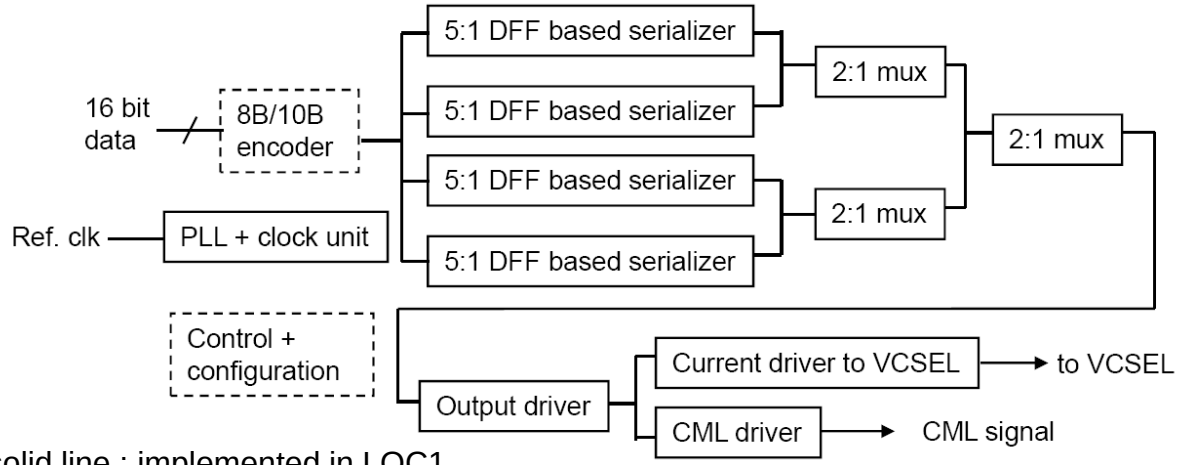
Digital Test of the Front-End

- 2 independent clocks
  - "TTC"-like clock for ADC and ADC multiplexer
  - crystal derived clock for high speed components (MUX, serializer)
    → provides much better jitter control
- Gray code control to manage multiplexer addresses
  - minimize effect of upsets
- data spends less than 8 bunch crossings in ADC multiplexer
  - minimize upsets
- triple redundant MUX
- 8B/10B encoding at level of the serializer
- full DAQ chain tested with commercial components and debugged successfully

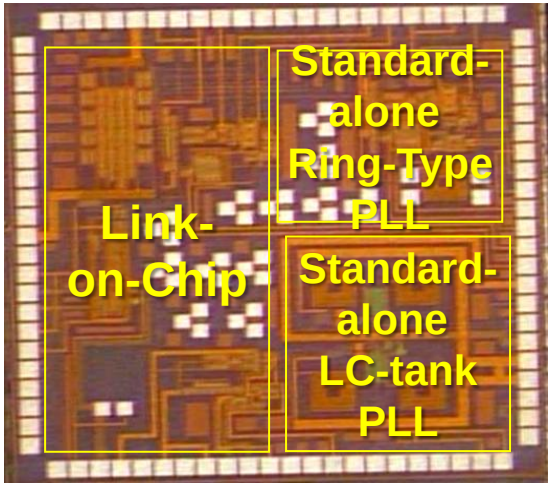




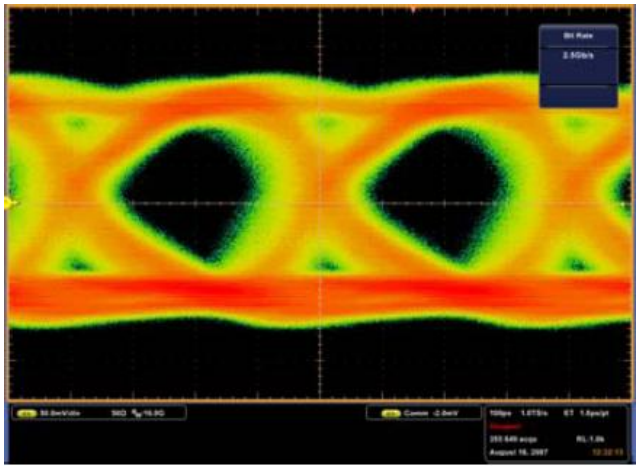
Link On Chip Prototype #1 (LOC1)



solid line : implemented in LOC1
dashed line: implemented in FPGA



- output rate at 2.5 Gb/s with 62.5 MHz reference clock
- power consumption ~200mW
- large jitter is observed and understood
  - deterministic jitter from 4-arm 2-stage MUX serializer
  - random jitter comes mostly from the PLL
  - will be corrected in the second prototype → LOC2
  - best BER reached ~10^{-11}
- SEE test with 200 MeV proton beam
  - error free for a fluence of 9×10^{9} p/cm^2
  - SEE cross section less than 10^{-10}cm^2 (p)
    - less than 1 error/link/h at sLHC
  - data analysis is ongoing and more tests are needed



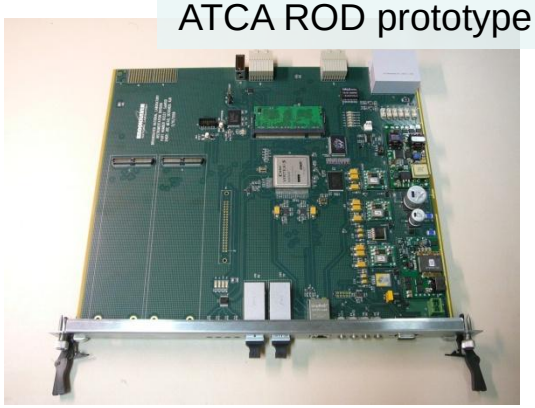
Eye diagram of a 2^7-1 pseudo random input data, UI = 400ps

High Performance Digital Readout

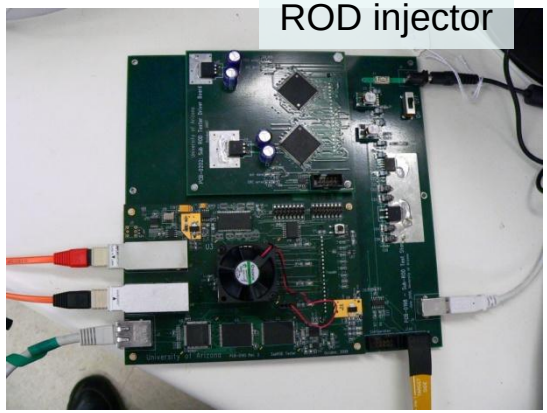
- AdvanceTCA 8U Module
  - fabric interface to implement 1/10 Gbit Ethernet, RapidIO or PCI Express protocol
  - update channel to facilitate the communication between adjacent modules
  - rear transition module interface for off-crate communication
- Xilinx Virtex 5 FX series FPGA (XC5VFX70T)
  - 6.5 Gbps RocketIO GTX transceiver
  - PowerPC 440 microprocessor up to 550MHz operation
  - 550MHz DSP48E slices
- 75Gbit/s parallel fiber optic transceiver
  - Reflex Photonics 75Gbit/s SNAP 12 InterBOARD parallel fiber optic transmitter and receiver
  - channel data rate of up to 6.25Gbit/s
- expansion slot on board

- ROD injector
  - Altera Statix GX II FPGA is capable of running 6.375 Gbit/s (and more) → next version in AMC mezzanine format
- performance test with previous prototype version:
  - 2.4Gbps link running stably
  - fixed pattern data transmission of 36 channels (over 12 fibers)

ATCA ROD prototype



ROD injector



→ more tests soon
with ATCA-format ROD